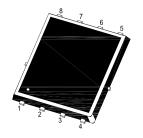
WTM503N015LS-AH

N-Channel Enhancement Mode MOSFET

Features

- AEC-Q101 Qualified
- Low R_{DS(ON)}
- · Low Miller Charge
- Halogen and Antimony Free(HAF), RoHS compliant

Gate Source



1.Source 2.Source 3.Source 4.Gate 5.Drain 6.Drain 7.Drain 8.Drain DFN5060 Plastic Package

Application

- · Motor/Body Load Control
- · Load Switch
- DC-DC converters and Off-line UPS

Key Parameters

Parameter	Value	Unit	
BV _{DSS}	30	V	
D Max	1.8 @ V _{GS} = 10 V	0	
R _{DS(ON)} Max	2.5 @ V _{GS} = 4.5 V	mΩ	
V _{GS(th)} typ	1.6	V	
Q _g typ	163 @ V _{GS} = 10 V	nC	

Absolute Maximum Ratings (at T_a = 25℃ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V_{GS}	V _{GS} ± 20	
Continuous Drain Current $T_c = 25^{\circ}\text{C}$ $T_c = 100^{\circ}\text{C}$	l _D	110 70	А
Peak Drain Current, Pulsed 1)	I _{DM}	420	Α
Single Pulse Avalanche Current	I _{AS}	48.7	Α
Single Pulse Avalanche Energy 2)	Eas	119	mJ
Power Dissipation T _c = 25°C	P _{tot}	35	W
Power Dissipation	P _{tot}	2.5	W
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to + 150	°C

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Case	Rejc	3.6	°C/W
Thermal Resistance from Junction to Ambient 3)	Reja	50	°C/W

¹⁾ Pulse Test: Pulse Width ≤ 100 μs, Duty Cycle ≤ 2%, Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$ = 150°C.



 $^{^{2)}}$ Limited by $T_{J(MAX)},$ starting T_J = 25 °C, L = 0.1 mH, R_g = 25 $\Omega,\,I_D$ = 48.7 A, V_{GS} = 10 V.

³⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.

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Characteristics at T_c = 25°C unless otherwise specified

Characteristics at T _c = 25°C unless otherwise specifie Parameter	Symbol	Min.	Тур.	Max.	Unit
STATIC PARAMETERS			, ,,		
Drain-Source Breakdown Voltage at I _D = 250 μA	BV _{DSS}	30	-	-	V
Drain-Source Leakage Current at V _{DS} = 24 V	Ipss	-	-	1	μΑ
Gate Leakage Current at V _{GS} = ± 20 V	Igss	-	-	± 100	nA
Gate-Source Threshold Voltage at V_{DS} = V_{GS} , I_D = 250 μ A	V _{GS(th)}	1.2	-	2.5	V
Drain-Source On-State Resistance at V_{GS} = 10 V , I_D = 30 A at V_{GS} = 4.5 V , I_D = 15 A	R _{DS(on)}	- -	1.4 -	1.8 2.5	mΩ
DYNAMIC PARAMETERS					
Gate resistance at V _{DS} = 0 V, f = 1 MHz	Rg	-	0.54	-	Ω
Forward Transconductance at $V_{DS} = 5 \text{ V}$, $I_D = 20 \text{ A}$	G fs	-	61	-	S
Input Capacitance at V_{DS} = 15 V, V_{GS} = 0 V, f = 1 MHz	C _{iss}	-	7462	-	pF
Output Capacitance at V_{DS} = 15 V, V_{GS} = 0 V, f = 1 MHz	Coss	-	886	-	pF
Reverse Transfer Capacitance At $V_{DS} = 15 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$	C _{rss}	-	733	-	pF
Gate charge total at V_{DS} = 15 V, V_{GS} = 10 V, I_D = 30 A at V_{DS} = 15 V, V_{GS} = 4.5 V, I_D = 30 A	Qg	- -	163 80	- -	nC
Gate to Source Charge at V_{DS} = 15 V, V_{GS} = 10 V, I_D = 30 A	Q _{gs}	-	23.3	-	nC
Gate to Drain Charge at V_{DS} = 15 V, V_{GS} = 10 V, I_D = 30 A	Q_{gd}	-	36.7	-	nC
Turn-On Delay Time at V_{DS} = 16.5 V, V_{GS} = 10 V, I_D = 30 A, R_g = 3.3 Ω	t _{d(on)}	-	43	-	nS
Turn-On Rise Time at V_{DS} = 16.5 V, V_{GS} = 10 V, I_D = 30 A, R_g = 3.3 Ω	tr	-	71	-	nS
Turn-Off Delay Time at V_{DS} = 16.5 V, V_{GS} = 10 V, I_D = 30 A, R_g = 3.3 Ω	$t_{\sf d(off)}$	-	42	-	nS
Turn-Off Fall Time at V_{DS} = 16.5 V, V_{GS} = 10 V, I_D = 30 A, R_g = 3.3 Ω	t _f	-	12	-	nS
Body-Diode PARAMETERS			_	_	_
Drain-Source Diode Forward Voltage at $I_S = 1 A$, $V_{GS} = 0 V$	V _{SD}	-	-	1.2	V
Body-Diode Continuous Current	ls		-	110	Α
Body-Diode Continuous Current, Pulsed	I _{SM}	-	-	420	Α
Body Diode Reverse Recovery Time at Is = 20 A, di/dt = 100 A / μs	t _{rr}	-	27	-	nS
Body Diode Reverse Recovery Charge at $I_S = 20 \text{ A}$, di/dt = 100 A / μs	Qrr	-	15	-	nC



Electrical Characteristics Curves

Fig. 1 Typical Output Characteristic

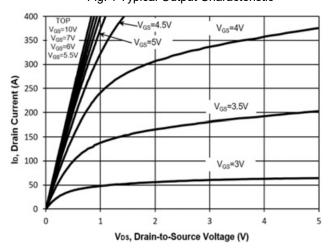


Fig. 2 Typical Transfer Characteristic

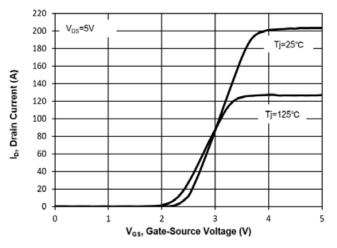


Fig. 3 on-Resistance vs. Drain Current

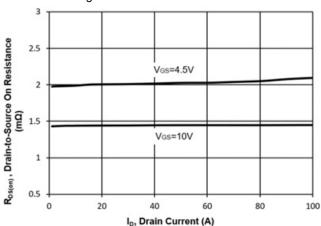


Fig. 4 on-Resistance vs. Gate Voltage

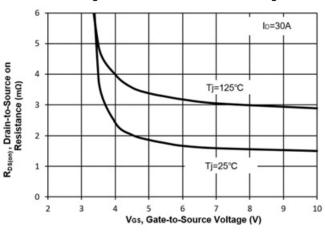


Fig. 5 on-Resistance vs.Ti

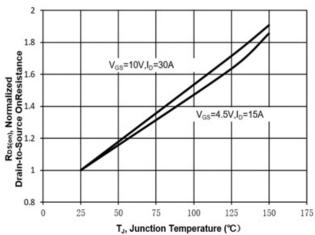
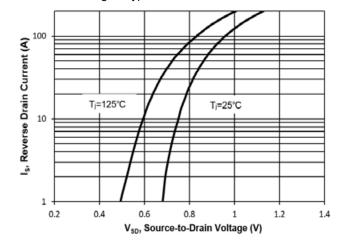


Fig. 6 Typical Forward Characteristic





Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

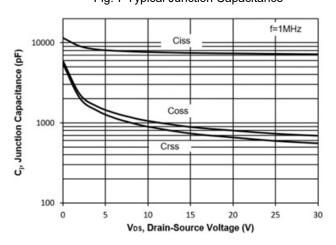


Fig. 8 Drain-Source Leakage Current vs. Tj

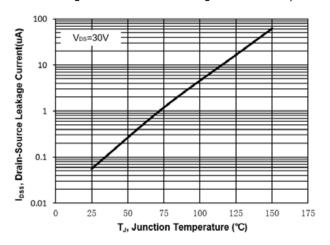


Fig. 9 V_{(BR)DSS} vs. Junction Temperature

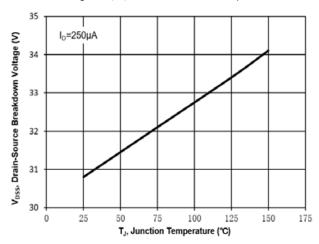


Fig. 10 Gate Threshold Variation vs. T_j

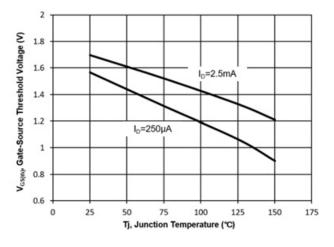
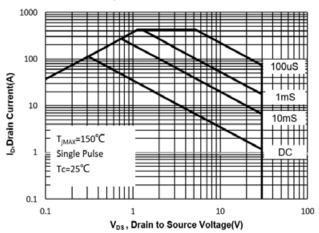


Fig. 11 Gate Charge 10 V_{DS}=15V I_D=30A V_{GS}, Gate-to-Source Voltage(V) 6 4 0 140 0 20 40 60 80 100 120 160 180 Q_g, Total Gate Charge(nC)

Fig. 12 Safe Operation Area





Electrical Characteristics Curves

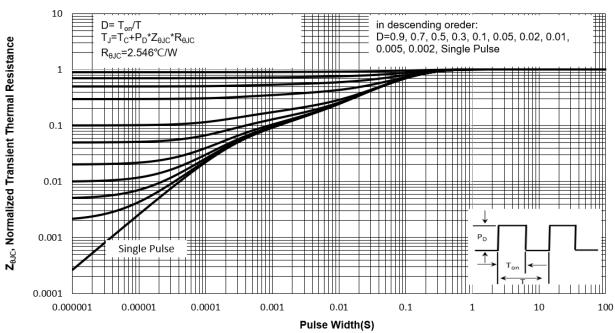
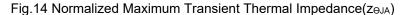
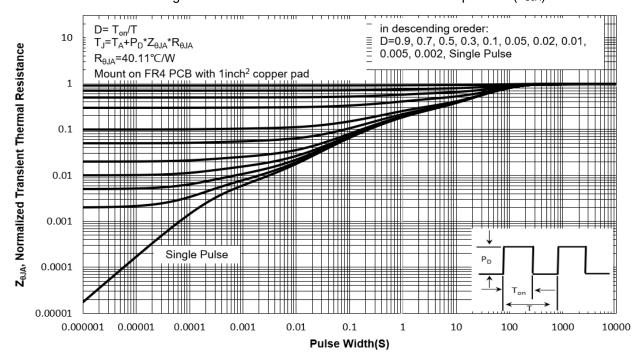


Fig.13 Normalized Maximum Transient Thermal Impedance(zeuc)

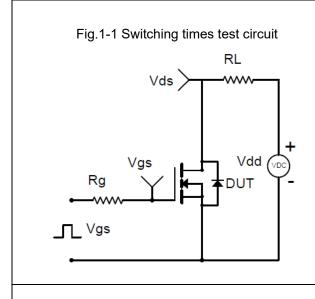






WTM503N015LS-AH

Test Circuits



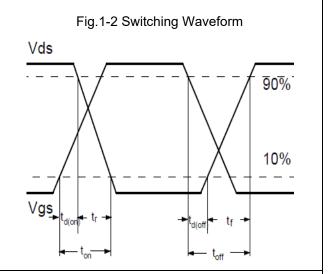


Fig.2-1 Gate charge test circuit

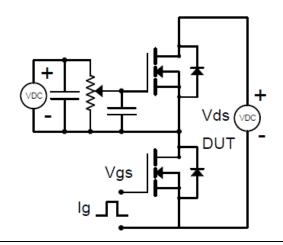


Fig.2-2 Gate charge waveform

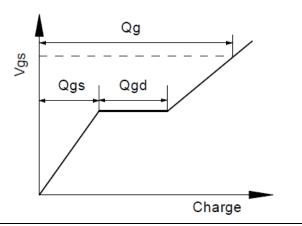


Fig.3-1 Avalanche test circuit

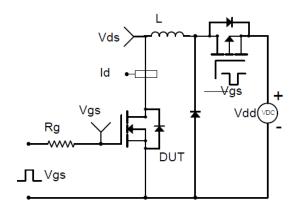
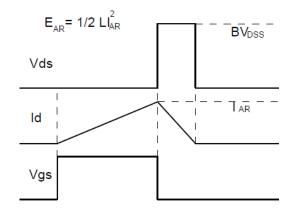


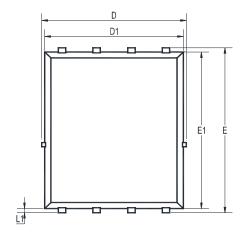
Fig.3-2 Avalanche waveform

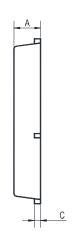


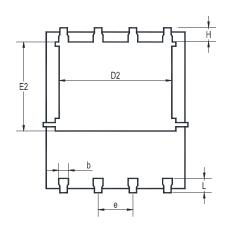


Package Outline Dimensions (Units: mm)

DFN5060

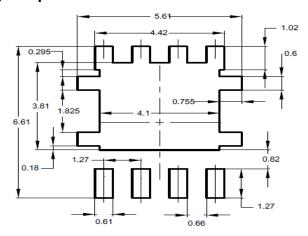






UNIT	Α	b	С	D	D1	D2	Е	E1	E2	е	L	L1	Н
no no	1.12	0.51	0.34	5.26	5.1	4. 5	6.25	6	3.66	1.37	0.71	0.2	0.71
mm	0.9	0.33	0.11	4.7	4.7	3.56	5.75	5.6	3.18	1.17	0.35	0.06	0.35

Recommended Soldering Footprint



Packing information

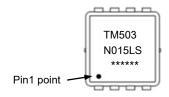
Package Tape Width		Pit	ch	Reel	Size	Per Reel Packing Quantity
Fackage	Package (mm)		inch	mm	inch	rei Neel Fackling Quantity
DFN5060	12	8 ± 0.1	0.315 ± 0.004	330	13	5,000

Marking information

" TM503N015LS " = Part No.

" ***** " = Date Code Marking

Font type: Arial





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